

SIDE LOOK PACKAGE SOLID STATE LAMP

MSL-824HG1

Description

The MSL-824HG1 is designed based on in an industry standard package for ease of handling and use.

The package is water clear epoxy within white plastic.

Applications

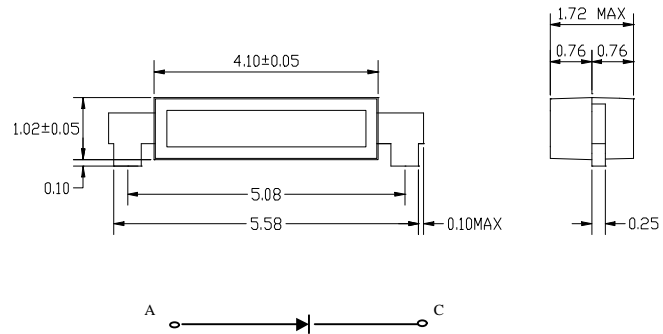
- LCD backlighting
- Symbol backlighting
- Front panel indicator

Features

- High performance
- Excellent chip to chip consistency
- High reliability

Package Dimensions

Units : mm



Notes :

1. All dimensions are in millimeters.
2. Tolerance is ± 0.1 mm unless otherwise noted.
3. Lead plating is minimum 80 micro inch of silver.

Absolute Maximum Ratings

@ $T_A=25^\circ\text{C}$

Parameter	Symbol	Maximum Rating	Unit
Power Dissipation	P_{ad}	100	mW
Peak Forward Current (1/100 Duty Cycle 1Khz pulse)	I_{pf}	120	mA
Continuous Forward Current	I_{af}	30	mA
Reverse Current ($V_R=5V$)	I_R	100	μA
Operating Temperature Range	T_{opr}	-40°C to +85°C	
Storage Temperature Range	T_{stg}	-40°C to +85°C	
Lead Soldering Temperature 260°C for 5 second (2.0mm From Body)			

UNI

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Optical-Electrical Characteristics

PART NO	Color		Dominant Wave Length $\lambda_D(\text{nm})$	Spectral Halfwidth $\Delta\lambda(\text{nm})$	Forward Voltage @ $I_F=20\text{mA}$ (V)		Luminous Intensity @ $I_F=20\text{mA}$ (mcd)		Viewing Angle $2\theta_{1/2}$ (deg)
	Emitted	Lens			TYP	MAX	MIN	TYP	

Typical Optical-Electrical Characteristic Curves

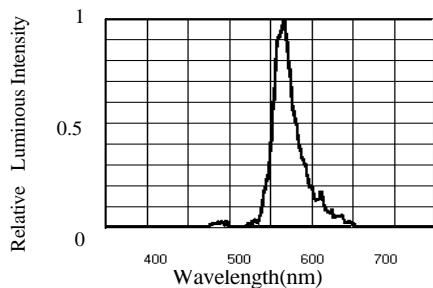


FIG.1 RELATIVE LUMINOUS INTENSITY VS. WAVELENGTH

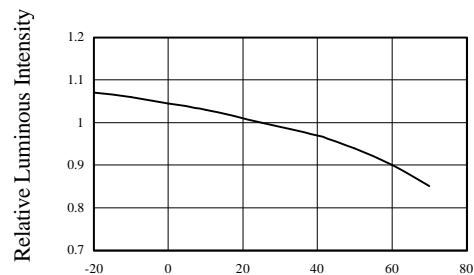


FIG.2. LUMINOUS INTENSITY VS. AMBIENT TEMPERATURE

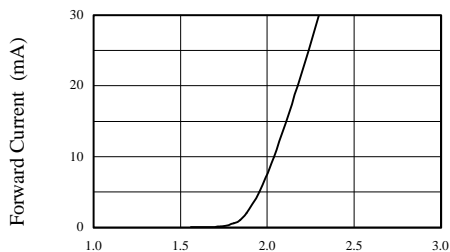


FIG.3 FORWARD CURRENT VS. FORWARD VOLTAGE

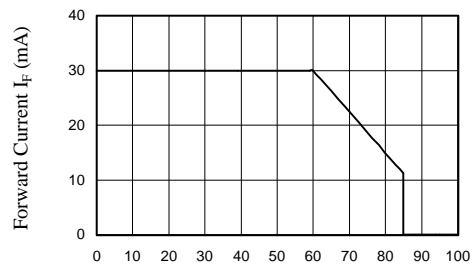


FIG.4 FORWARD CURRENT VS. AMBIENT TEMPERATURE

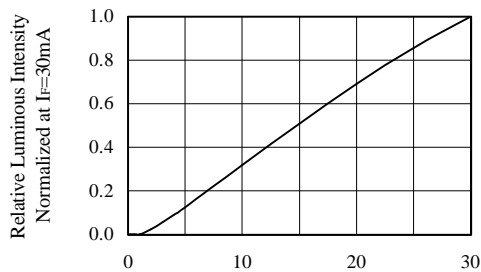


FIG.5 RELATIVE LUMINOUS INTENSITY VS. FORWARD CURRENT

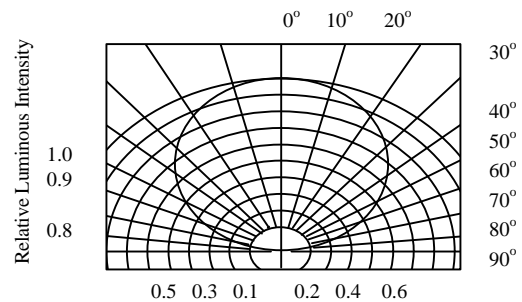


FIG.6 RADIATION PATTERN DIAGRAM